

# Circuit Module having Interleaved Groups of Circuit Chips

## ABSTRACT

5 A circuit module has a carrier (10) and multiple stacks of  
circuit chips arranged on a surface of the carrier. Each  
stack has multiple circuit chips arranged in different  
layers. The circuit chips are grouped in different groups,  
wherein the groups are not active at the same time. The  
10 circuit chips are arranged such that circuit chips belonging  
to the same group are arranged in different layers in  
adjacent stacks.

Fig. 1